ROHS

LEADER TIME SRL

PRODUCT SPECIFICATION

20*4 Characters COB LCD MODULE MODEL: LT-2004C-801 Ver:1.0

< >> Finally Specification

CUSTOMER'S APPROVAL								
CUSTOMER:								
SIGNATURE: DATE:								

APPROVED	РМ	PD	PREPARED
ВҮ	REVIEWD	REVIEWD	Ву

Prepared By: LEADER TIME SRL

VIA MONS. PROSDOCIMI, 27 36042 BREGANZE (VI)

• This specification is subject to change without notice. Please contact LT or it's representative before designing your product based on this specification.

1/1

Revision Status

Version	Revise Date	Page	Content	Modified By
Ver. 1.0	2008.07.03		First Issued	
		l		

Table of Contents

No. Contents	Page
1. FEATURES	4
2. MECHANICAL SPECIFICATIONS	4
3. ELECTRICAL SPECIFICATIONS	4
4. TERMINAL FUNCTIONS AND BLOCK DIAGRAM	6
5. TIMING CHARACTERISTICS	7
6. COMMAND LIST	8
7. QUALITY SPECIFICATIONS	9
8. CHARACTER GENERATOR ROM	14
9. RELIABILITY	15
10. HANDLING PRECAUTION	16
11. OUTLINE DIMENSION	17

1. Features

The features of LCD are as follows

* Display mode : STN/ Blue, Transfmissive, Negative * Controller IC : SPLC780D1-001A (English-Japanese)

* Display format : 20X4 Characters

* Interface Input Data : 8 Bit

* Driving Method : 1/16Duty, 1/4Bias

* Viewing Direction : 6 O'clock

* Backlight : LED Unit (White)
* Sample NO. : EC2004A1_08

2. MECHANICAL SPECIFICATIONS

Item	Specification	Unit
Module Size	146(W) x62.5(H) x13.6MAX(T)	mm
Viewing Area	123.5(W) x 43(H)	mm
Activity Area	118.84(W)x38.47(H)	mm
Character Font	5x7 Dots with cursor	-
Character Size	4.84(W)x9.22(H)	mm
Character Pitch	6.00(W)x9.75(H)	mm
Dot Size	0.92(W)x1.10(H)	mm

3. ELECTRICAL SPECIFICATIONS

3-1 ABSOLUTE MAXIMUM RATINGS (Ta = 25 °C)

Item	Symbol	Sta			
item	Symbol	Min.	Тур.	Max.	Unit
Supply Voltage For Logic	Vdd - Vss	-0.3	5.0	7	V
upply Voltage For LCD Drive	V _{OP} = V _{DD} -V ₀	V _{DD} -10	-	V _{DD} +0.3	V
Input Voltage	Vin	-0.3	-	VDD+0.3	V
Operating Temp.	Тор	-20	-	+70	Ĉ
Storage Temp.	Tst	-30	-	+80	°C

^{*.} NOTE: The response time will be extremely slow when the operating temperature is around -10 $^{\circ}$ C, and the back ground will become darker at high temperature operating.

3-2 ELECTICAL CHARACTERISTICS

3-2-1.DC CHARACTERISTICS(VDD=4.5V~5.5V,Ta=25°C)

ltem		Symbol	Test Condition	Min.	Тур.	Max.	Unit
Logic supply Voltage		V _{DD} – V _{ss}	Ta = 25 °C	4.5	5	5.5	V
LCD Dri	LCD Drive			-	4.5	-	V
Input Voltage	"H" Level	V _{IH}	VDD=5V ± 5%	0.7Vdd	-	Vdd	V
	"L" Level	V _{IL}		-0.3	-	0.55	V
Frame Frequency		f _{FLM}	VDD = 5V	-	-	78.1	Hz
Current Cons	umption	I _{DD}	VDD =5V	-	2.2	-	mA

3-3. BACKLIGHT

3-3-1. Absolute Maximum Ratings

Item	Symbol	Condition	min	Тур	Max	Unit
Forward Current	IF		-	-	120	mA
Reverse Voltage	VR	Ta = 25 °C	-	-	5	V
Power Dissipation	PD		-	-	408	mW

3-3-2. Electrical-optical Characteristics

Item	Symbol	Condition	min		Тур		Max		Unit
Forward Voltage	VF	If=120mA	2.9		3.2		3.4		\/
Forward Voltage	VF	Ta = 25 °C							V
Average Luminous Intensity	lv	Ta = 25 °C If=120mA	-		12	20		-	cd/m ²
Co lour coordinate	_	Ta = 25 °C	Χ	Υ	Х	Υ	Χ	Υ	_
Co lour coordinate		If=120mA	-	-	0.28	0.29	-	-	_

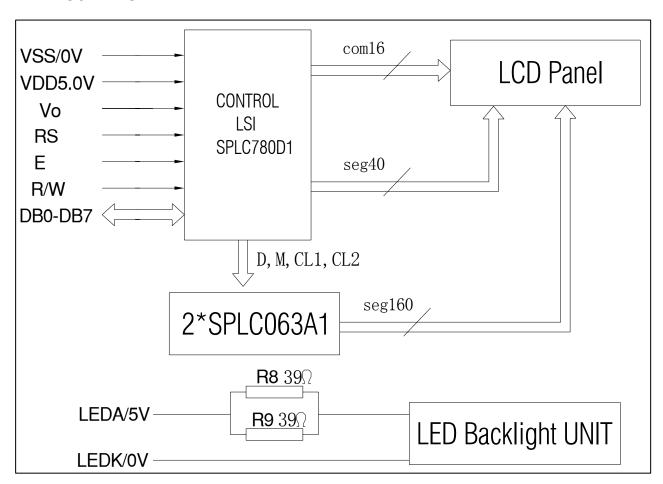
The brightness is measured without LCD panel

4. TERMINAL FUNCTIONS AND BLOCK DIAGRAM

4-1. INTERFACE PIN FUNCTION DESCRIPTION

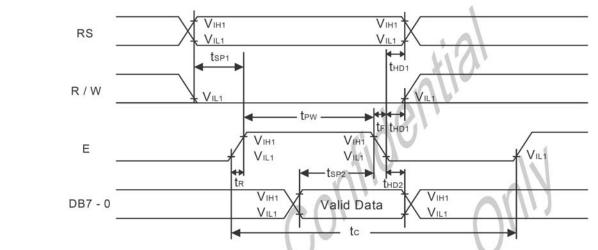
PIN NO.	SYMBOL	FUNCIONS
1	vss	Ground
2	VDD	Supply voltage for logical circuit/5.0V
3	V0	Supply voltage for LCD driving
		A signal for selecting registers.
4	RS	1: Data Register (for read and write)
		0: Instruction Register (for write)
5	R/W	A signal for selecting read or write actions.1: Read, 0: Write.
6	E	Enable signal for reading or writing data.
7-14	DB0-DB7	8 Bit Data Bus
15	LED-A	Backlight (+)/5.0V
16	LED-K	Backlight (-) /0V
17-18	NC	No connect

4-2. BLOCK DIAGRAM



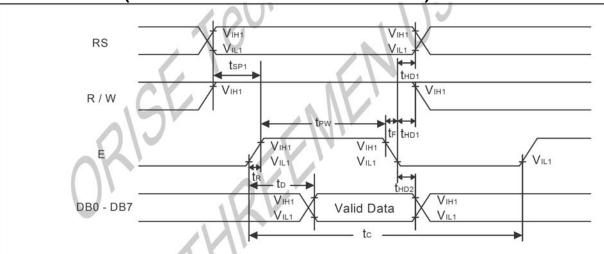
5. TIMING CHARACTERISTICS

5-1. Write mode (Write Data from MPU to SPLC780D1)



Characteristics			Limit			
	Symbol	Min.	Тур.	Max.	Unit	Test Condition
E Cycle Time	tc	400	-	17.0	ns	Pin E
E Pulse Width	t _{PW}	150	-	-	ns	Pin E
E Rise/Fall Time	t _R , t _F	-	-	25	ns	Pin E
Address Setup Time	t _{SP1}	30	127	-10	ns	Pins: RS, R/W, E
Address Hold Time	t _{HD1}	10	-	JAK	ns	Pins: RS, R/W, E
Data Setup Time	t _{SP2}	40	-	CIL	ns	Pins: DB0 - DB7
Data Hold Time	t _{HD2}	10	- /	1110	ns	Pins: DB0 - DB7

5-2. Read mode(Read Data from SPLC780D1 to MPU)



Observants vistina	Oh.al		Limit		1114	Total Constitution
Characteristics	Symbol	Min.	Тур.	Max.	Unit	Test Condition
E Cycle Time	tc	400		-	ns	Pin E
E Pulse Width	t _W	150	-	- 4	ns	Pin E
E Rise/Fall Time	t _R , t _F	DV.	-	25	ns	Pin E
Address Setup Time	t _{SP1}	30		. 1	ns	Pins: RS, R/W, E
Address Hold Time	t _{HD1}	10	/		ns	Pins: RS, R/W, E
Data Output Delay Time	t _D	-	- 4	100	ns	Pins: DB0 - DB7
Data hold time	t _{HD2}	5.0	A- N	J'-	ns	Pin DB0 - DB7

6. COMMAND LIST

				Ins	tructi	on Co	ode						ecution tin	
Instruction	RS	RW	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0	Description	Fosc= 190KHz	Fosc= 270KHz	Fosc= 350KHz
Clear Display	0	0	0	0	0	0	0	0	0	1	Write "20H" to DDRAM and set DDRAM address to "00H" from AC	2.16ms	1.52ms	1.18ms
Return Home	0	0	0	0	0	0	0	0	3		Set DDRAM address to "00H" from AC and return cursor to its original position if shifted. The contents of DDRAM are not changed.	2.16ms	1.52ms	1.18ms
Entry Mode Set	0	0	0	0	0	0	0	7	I/D	S	Assign cursor moving direction and enable the shift of entire display	53µs	38μs	29µs
Display ON/ OFF Control	0	0	0	0	0	0	1	D	С	В	Set display (D), cursor(C), and blinking of cursor(B) on/off control bit.	53μs	38µs	29μs
Cursor or Display Shift	٥	0	0	0	0	1	S/C	R/L			Set cursor moving and display shift control bit, and the direction, without changing of DDRAM data.	53μs	38μs	29μs
Function Set	0	0	0	0		DL	Z	F	9		Set interface data length (DL: 8-bit/4-bit), numbers of display line (N: 2-line/1-line) and, display font type (F:5x10 dots/5x8 dots)	53µs	38µs	29µs
Set CGRAM Address	0	0	0	1	AC5	AC4	AC3	AC2	AC1	AC0	Set CGRAM address in address counter.	53µs	38µs	29μs
Set DDRAM Address	0	0	1	AC6	AC5	AC4	AC3	AC2	AC1	AC0	Set DDRAM address in address counter	53µs	38µs	29μs
Read Busy Flag and Address Counter	0	1	BF	AC6	AC5	AC4	AC3	AC2	AC1	AC0	Whether during internal operation or not can be known by reading BF. The contents of address counter can also be read.			
Write Data to RAM	1	0	D7	D6	D5	D4	D3	D2	D1	D0	Write data into internal RAM (DDRAM/CGRAM).	53μs	38µs	29µs
Read Data from RAM	1	1	D7	D6	D5	D4	D3	D2	D1	D0	Read data from internal RAM (DDRAM/CGRAM).	53µs	38µs	29µs

Note1: "--": don't care

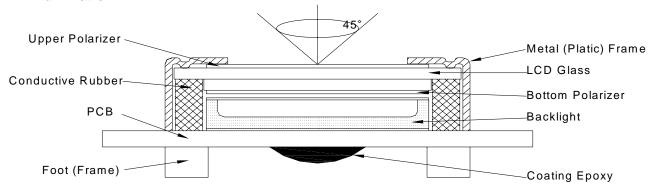
Note2: In the operation condition under -20°C ~ 75°C, the maximum execution time for majority of instruction sets is 100us, except two instructions, "Clear Display" and "Return Home", in which maximum execution time can take up to 4.1ms.

7.CHARACTER GENERATOR ROM(SPLC780D1-001A)

Upper 4 bit Lower 4 bit	LLLL	LLLH	LLHL	LLHH	LHLL	LHLH	LHHL	LHHH	HLLL	HLLH	HLHL	ШН	ниг	ннін	нинг	нинн
LLLL																
lllH																
LLHL																
ггнн			Ħ													
LHLL																
LHLH																
гннг																
1. Н Н Н																
HLLL																
нггн																
HLHL																
нцнн																
HHLL																
ннгн																
нннг																
нннн																

8. QUALITY SPECIFICATIONS

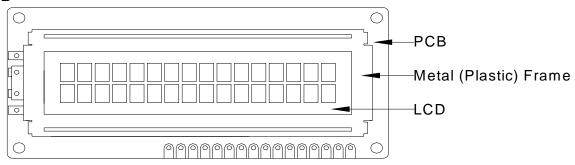
- 8 1. LCM Appearance and Electric inspection Condition
 - 1. Inspection will be done by placing LCM 30cm away from inspector's eyeballs under normal illumination.



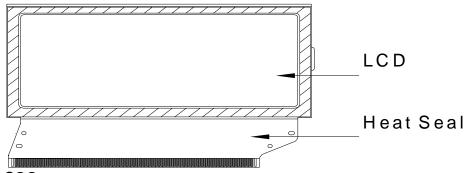
2. View Angle: with in 45° around perpendicular line.

8-2. Definition

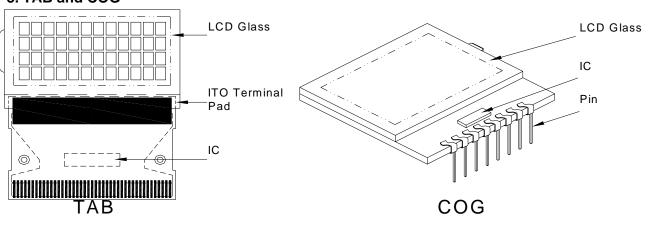
1. COB



2. Heat Seal



3. TAB and COG



Issued Date: 2008/07/03

Doc. No.:

8-3. Sampling Plan and Acceptance

1.Sampling Plan

MIL - STD - 105E (||) ordinary single inspection is used.

2.Acceptance

Major defect: AQL = 0.25%Minor defect: AQL = 0.65%

8-4. Criteria

1.COB

Defect	Inspection Item	Inspection Standards	
Major	PCB copper flakes peeling off	Any copper flake in viewing Area should be greater than 1.0mm ²	Reject
Major	Height of coating epoxy	Exceed the dimension of drawing	Reject
Major	Void or hole of coating epoxy	Expose bonding wire or IC	Reject
Major	PCB cutting defect	Exceed the dimension of drawing	Reject

2.SMT

2. SM I	Increation Item	Inspection Standards			
Defect	Inspection Item	inspection Standa	arus		
Minor	Component marking not readable		Reject		
Minor	Component height	Exceed the dimension Of drawing	Reject		
Major	Component solder defect (missing, extra, wrong component or wrong orientation		Reject		
Minor	Component position shift component soldering pad X D Y Y	X < 3/4Z Y > 1/3D	Reject Reject		
Minor	Component tilt component soldering pad	Y > 1/3D	Reject		
Minor	Insufficient solder component PAD	<i>θ</i> ≤ 20°	Reject		

3. Metal (Plastic) Frame

Defect	Inspection Item	lı lı	nspection Standa	rds			
Major	Crack / breakage	Any	ywhere	Reject			
		W	L	Acceptable of Scratch			
		w<0.1mm	Any	Ignore			
		0.1 <u><</u> w<0.2mm	L <u><</u> 5.0mm	2			
Minor	Frame Scratch	0.2 <u><</u> w<0.3mm	L <u><</u> 3.0mm	1			
_		w <u>></u> 0.3mm	Any	0			
		Note: 1. Above criteria applicable to scratch lines with distance greater than 5mm. 2. Scratch on the back side of frame (no visible) can be ignored.					
				Acceptable of Dents / Pricks			
		Φ≤	2				
	Frame Dent , Prick	1.0<	1				
Minor	$\Phi = \frac{L + W}{2}$	1.5	0				
	2	Note: 1. Above criteria applicable to any two dents / pricks with distance greater than 5mm 2. Dent / prick on the back side of frame (not visible) can be ignored					
Minor	Frame Deformation	Exceed the dimension of drawing					
Minor	Metal Frame Oxidation		Any rust				

4. Flexible Film Connector (FFC)

Defect	Insp	ection Item	Inspection Standards			
Minor	Tilted soldering		Within the angle +5°	Acceptable		
Minor	Uneven s	older joint /bump		Reject		
			Expose the conductive line	Reject		
Minor	Hole	$\Phi = \frac{L + W}{2}$	Ф > 1.0mm	Reject		
Minor	Y - \frac{1}{2}	sition shift	Y > 1/3D	Reject		
IVIIIIOF	A J	- 	X > 1/2Z	Reject		

5. Screw

51 00.011				
Defect	Inspection Item	Inspection Standards		
Major	Screw missing/loosen		Reject	
Minor	Screw oxidation	Any rust	Reject	
Minor	Screw deformation	Difficult to accept screw driver	Reject	

6. Heat-seal \ TCP \ FPC

Defect	Inspection Item	Inspection Standards		
Major	Scratch expose conductive layer		Reject	
Minor	HS Hole $\Phi = \frac{L + W}{2}$	Φ> 0.5mm	Reject	
Major	Adhesion strength	Less than the specification	Reject	
Minor	Position shift y y D D	Y > 1/3D	Reject	
Minor	T X	X > 1/2Z	Reject	
Major	Conductive line break		Reject	

7. LED Backing Protective Film and Others

Defect	Inspection Item	Inspection Standards					
		Acceptable number of units					
		Φ <u><</u> 0.10mm	Ignore				
		0.10<⊕ <u><</u> 0.15mm	2				
Minor	LED dirty, prick	0.15<⊕ <u><</u> 0.2mm	1				
		Φ>0.2mm	0				
		The distance between any two spots should be ≥5mm Any spot/dot/void outside of viewing area is acceptable					
Minor	Protective film tilt	Not fully cover LCD	Reject				
Major	COG coating	Not fully cover ITO circuit	Reject				

8. Electric Inspection

Defect	Inspection Item	Inspection Standards			
Major	Short		Reject		
Major	Open		Reject		

9. Inspection Specification of LCD

Defect	Insp	ect Item		Inspection Standards					
		* Glass Scratch	W	_	≤0.03	0.0	0.0 <u><!--</u--></u>	5 V	V>0.05
		* Polarizer Scratch	L	L	_<5		L<3		Any
Minor	Linear Defect	* Fiber and Linear	ACC. NO.	1			1		Reject
		material	Note	L is the le	ngth and V	/ is th	e width of	the de	efect
		* Foreign material		Φ <u><</u> 0.1		.15 (0.15<⊕ <u><</u> 0.	.2	Φ>0.2
	Black Spot and	between glass and polarizer or glass		3EA / 100mm ²	2		1		0
Minor	Polarizer Pricked	and glass * Polarizer hole or protuberance by external force	Note	Φ is the average diameter of the defect. Distance between two defects > 10mm.					
		* Unobvious	Φ	Φ<	<u>:</u> 0.3	0.3	<⊕ <u><</u> 0.5	0.	5<⊕
	White Spot	transparant foreign material between	ACC. NO.	3EA / 1	00mm ²		1		0
Minor			Note		is the average diameter of the defect. Distance between two defects > 10mm.				
			Φ	Φ <u><</u> 0.10	0.10<⊕ <u><</u>	0.20	0.20<⊕≤	0.25	⊕>0.25
		W		3EA / 100mm ²	2		1		0
Minor	Segment Defect			W is more	e than 1/2 s	egme	ent width		Reject
	26.66		Note	dote $\Phi = \frac{-L + W}{2}$ Distance between two defect is				m	
			Φ	Φ <u><</u> 0.10	0.10<Ф<	0.20	0.20<⊕≤	0.25	Φ>0.25
	Protuberant	Protuberant		Glue	W <u><</u> 1/2 \$ W <u><</u> 0.		W <u><</u> 1/2 3 W <u><</u> 0.		Ignore
Minor	Segment	$\Phi = (L + W)/2$	ACC. NO.	3EA / 100mm ²	2		1		0
			1. Seg	ment	•				
			В		<u><</u> 0.4mm		3 <u><</u> 1.0mm		1.0mm
	Assembly		B-	A B	-A<1/2B	B-	A<0.2	B-A	N<0.25
Minor	Mis-alignment	P - P		Judge Acceptable		Acc	Acceptable Acceptable		
			2. Dot Matrix						
	_		Deformation>2°					Reject	
Minor	Stain on LCD Panel Surface		Accept when stains can be wiped lightly with a soft clotl or a similar one. Otherwise, judged according to the above items: "Black spot" and "White Spot"						

14/17 **Model No.:** EC2004A1SGW6B **Ver:**1.0

9. RELIABILITY

NO.	Item	Condition	Criterion		
1	High Temperature Operating	70°C, 96Hrs			
2	Low Temperature Operating	-20℃, 96Hrs			
3	High Humidity	60°C, 90%RH, 96Hrs			
4	High Temperature Storage	80°C, 96Hrs			
5	Low Temperature Storage	-30℃, 96Hrs	No defect in cosmetic and operational functi		
		Random wave	on allowable.		
6	Vibration	10 ~ 100Hz	Total current Consumption should be below doub		
	VIDIALIOII	Acceleration: 2g	le of initial value.		
		2 Hrs per direction(X,Y,Z)			
		-20°C to 25°C to 70°C			
7	Thermal Shock	(60Min) (5Min) (60Min)			
		16Cycles			
		Contract Discharge Voltage: +1 ~ 5kV and -1 ~ -5kV	There will be		
8	ESD Testing	JAN AND TO STAN	discharged ten times at every discharging		
		Air Discharge Voltage: +1 ~ 8kV and -1 ~ -8kV	voltage cycle. The voltage gap is 1kV.		

Note: 1) Above conditions are suitable for Our Company standard products.
2) For restrict products, the test conditions listed as above must be revised.

10. HANDLING PRECAUTION

(1) Mounting Method

The panel of the LCD Module consists of two thin glass plates with polarizers which easily get damaged since the Module is fixed by utilizing fitting holes in the printed circuit board. Extreme care should be taken when handling the LCD Modules.

(2) Caution of LCD handling & cleaning

When cleaning the display surface, use soft cloth with solvent (recommended below) and wipe lightly.

- Isopropyl alcohol
- Ethyl alcohol
- Trichloro trifloro thane

Do not wipe the display surface with dry or hard materials that will damage the polarizer surface. Do not use the following solvent:

- Water
- Ketone
- Aromatics
- (3) Caution against static charge

The LCD Module use C-MOS LSI drivers, so we recommend that you connect any unused input terminal to VDD or VSS, do not input any signals before power is turned on. And ground your body, Work/assembly table. And assembly equipment to protect against static electricity.

(4) Packaging

- Modules use LCD elements, and must be treated as such. Avoid intense shock and falls from a height.
- To prevent modules from degradation. Do not operate or store them exposed directly to sunshine or high temperature/humidity.

(5) Caution for operation

- It is indispensable to drive LCD's within the specified voltage limit since the higher voltage than the limit shorten LCD life. An electrochemical reaction due to direct current causes LCD deterioration, Avoid the use of direct current drive.
- Response time will be extremely delayed at lower temperature than the operating temperature range and on the other hand at higher temperature LCD's show dark color in them. However those phenomena do not mean malfunction or out of order with LCD's. Which will come back in the specified operating temperature range.
- If the display area is pushed hard during operation, some font will be abnormally displayed but it resumes normal condition after turning off once.
- A slight dew depositing on terminals is a cause for electro-chemical reaction resulting in terminal open circuit.

Usage under the relative condition of 40°C, 50%RH or less is reequired.

(6) Storage

In the case of storing for a long period of time (for instance.) For years) for the purpose or replacement use, The following ways are recommended.

- Storage in a polyethylene bag with sealed so as not to enter fresh air outside in it, And with no desiccant.
- Placing in a dark place where neither exposure to direct sunlight nor light is. Keeping temperature in the specified storage temperature range.
- Storing with no touch on polarizer surface by the anything else. (It is recommended to store them as they have been contained in the inner container at the time of delivery)

(7) Safety

- It is recommendable to crash damaged or unnecessary LCD into pieces and wash off liquid crystal by using solvents such as acetone and ethanol.

Which should be burned up later.

- When any liquid crystal leaked out of a damaged glass cell comes in contact with your hands, please wash it off well with soap and water.

11. OUTLINE DIMENSION

